TOSHIBA Power Transistor Module Silicon NPN&PNP Epitaxial Type (Six Darlington Power Transistors inOne)

MP6301

High Power Switching Applications

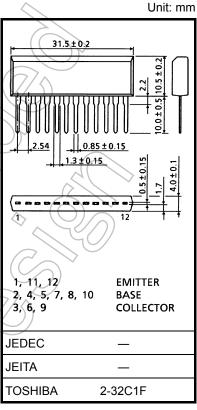
3-Phase Motor Drive and Bipolar Drive of Pulse Motor

- Small package by full molding (SIP 12 pins)
- High collector power dissipation (6-device operation)
 PT = 4.4 W (Ta = 25°C)
- High collector current: $I_{C(DC)} = \pm 3 \text{ A (max)}$
- High DC current gain: $h_{FE} = 2000$ (min) ($V_{CE} = \pm 2 \text{ V}$, $I_{C} = \pm 1 \text{ A}$)

Absolute Maximum Ratings (Ta = 25°C)

				/ 0 / .
ce	Symbol	Rat	Unit	
us .	Symbol	NPN	PNP	Gill
Collector-base voltage			-100	V
	V _{CEO}	80 <	-80	>
Emitter-base voltage			-8>	V
DC	Ic	m	-3	Δ_
Pulse	I _{CP}	5)	> −5	
	I _B	0.5	-0.5	A
on	PC)) 2	.0	w
on	PT	4	.4]/w
((7/ \ Tj	15	50	°C
ge	T _{stg}	-55 t	o 150	°c
		VCBO VCEO VEBO DC IC Pulse ICP IB On PC Tj	NPN VCBO 100 VCEO 80 VEBO 8 NEW Section NPN NPN	NPN PNP VCBO 100 -100 VCEO 80 -80 VEBO 8 -8 PNE VEBO 8 -3 PUlse ICP 5 -5 On PC 2.0 On PT 4.4 Tj 150 TE TE TE TE TE TE TE T

Industrial Applications

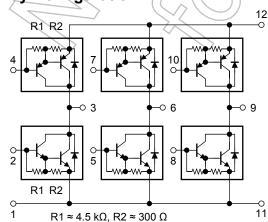


Weight: 3.9 g (typ.)

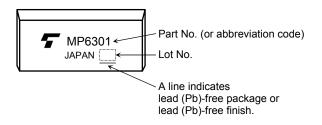
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Array Configuration



Marking



Thermal Characteristics

Characteristics	Symbol	Max	Unit	
Thermal resistance from junction to ambient	ΣR _{th (j-a)}	28.4	°C/W	
(6-device operation, Ta = 25°C)	()/			
Maximum lead temperature for soldering purposes	TL	260	°c (
(3.2 mm from case for 10 s)				

Electrical Characteristics (Ta = 25°C) (NPN transistor)

ı		, 		~//			
Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off cu	rrent	I _{CBO} <	V _{CB} = 100 V, I _E = 0 A	_	_	20	μΑ
Collector cut-off cu	rrent	ICEO	V _{CE} = 80 V, I _B = 0 A	-	_	20	μΑ
Emitter cut-off curre	ent	I _{EBO}	V _{EB} = 8 V, I _C = 0 A	0.8	1	4.0	mA
Collector-base brea	akdown voltage	V (BR) CBO	I _C = 1 mA, I _E = 0 A	100	ı	1	>
Collector-emitter br	eakdown voltage	V (BR) CEO	I _C = 10 mA, I _B = 0 A	80	1	-	٧
DC current gain		hFE (1)	V _{CE} = 2 V, I _C = 1 A	2000	ı	1	
Do current gam		hFE (2)	V _{CE} = 2 V, I _C = 2 A	1000	1	1	
Saturation voltage -	Collector-emitter	V _{CE} (sat)	I _C = 2 A, I _B = 4 mA	_	_	1.8	V
	Base-emitter	V _{BE (sat)}	$I_C = 2 \text{ mA}$, $I_B = 4 \text{ mA}$	_	_	2.3	
Transition frequency		fr	$V_{CE} = 2 \text{ V}, I_{C} = 0.5 \text{ A}$	_	100	_	MHz
Collector output capacitance		C _{ob}	V _{CB} = 10 V, I _E = 0 A, f = 1 MHz	ı	20	1	pF
	Turn-on time	ton	Output	l	0.4	l	
Switching time	Storage time	t _{stg}	20 µs B2 V _{CC} = 30 V	1	3.0	_	μs
	Fall time	t _f	$I_{B1} = -I_{B2} = 4 \text{ mA, duty cycle} \le 1\%$		0.6	_	



Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I _{FM}	_	_	_	3	Α
Surge current	I _{FSM}	t = 1 s, 1 shot	_	_	5	Α
Forward voltage	V _F	I _F = 1 A, I _B = 0 A	1	_	2.0	٧
Reverse recovery time	t _{rr}	I _F = 3 A, V _{BE} = -3 V, dI _F /dt = -50 A/μs		1	-	μs
Reverse recovery charge	Q _{rr}	1F - 3 A, VBE3 V, αιέ/αι30 Ανμδ	7) \ 5	_	μC

Electrical Characteristics (Ta = 25°C) (PNP transistor)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off cu	rrent	I _{CBO}	V _{CB} = -100 V, I _E = 0 A	_		-20	μΑ
Collector cut-off cu	rrent	I _{CEO}	V _{CE} = -80 V, I _B = 0 A		4	-20	μΑ
Emitter cut-off curre	ent	I _{EBO}	V _{EB} = -8 V, I _C = 0 A	-0.8	5-/	-4.0	mA
Collector-base brea	akdown voltage	V (BR) CBO	I _C = -1 mA, I _E = 0 A	-100	2/5) —	V
Collector-emitter br	reakdown voltage	V (BR) CEO	$I_C = -10 \text{ mA}, I_B = 0 \text{ A}$	-80	90	_	٧
DO		h _{FE (1)}	$V_{CE} = -2 V, I_{C} = -1 A$	2000		_	
DC current gain		h _{FE (2)}	V _{CE} = -2 V, I _C = -2 A	1000	_	_	
Caturation valtage	Collector-emitter	V _{CE} (sat)	I _C = -2 A, I _B = -4 mA	\ -	_	-1.8	V
Saturation voltage	Base-emitter	V _{BE (sat)}	I _C = -2 A, I _B = -4 mA	/ _	_	-2.3	
Transition frequency		f _T	$V_{CE} = -2 \text{ V}, I_{C} = -0.5 \text{ A}$	_	50	_	MHz
Collector output capacitance		C _{ob}	V _{CB} = -10 V, I _E = 0 A, f = 1 MHz	_	30	_	pF
	Turn-on time	ton	Output Input	_	0.4	_	
Switching time	Storage time	tstg	V _{CC} = -30 V	ı	1.8		μs
	Fall time	te	20 µs -I _{B1} = I _{B2} = 4 mA, duty cycle ≤ 1%		0.4		

Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	\wedge	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current		JFM.	_	_	_	3	Α
Surge current	7/	I _{FSM}	t = 1 s, 1 shot	_	_	5	Α
Forward voltage		V _F	I _F = 1 A, I _B = 0 A	_	_	2.0	V
Reverse recovery time		t _{rr}	I _F = 3 A, V _{BE} = 3 V, dI _F /dt = −50 A/μs	_	500	_	μs
Reverse recovery charge		Q _{rr}	1 - 3 A, VBE - 3 V, αιΕ/αι50 Α/μς	_	2.7	_	μC



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